

International Application No.: PCT/JP03/02161
U.S. Patent Application No.: Unknown
September 1, 2004
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IN THE ABSTRACT:

Please replace the Abstract of the Disclosure originally filed with the above-identified patent application with the following Abstract:

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ABSTRACT OF THE DISCLOSURE

A method of cutting a rare-earth alloy with a wire saw—**20**, obtained by fixing abrasive grains **24** on a core wire **22** with a resin layer—**26**, includes the step of moving the wire saw while a portion of the rare-earth alloy being machined with the wire saw is immersed in a coolant, which is mainly composed of water and has a surface tension of about 25 mN/m to about 60 mN/m at 25-about 25°C, thereby cutting the rare-earth alloy. In the wire saw, an average distance between two of the abrasive grains, which are adjacent to each other in a length direction, is about 150% to less than about 400% of the average grain size of the abrasive grains, an average height of portions of the abrasive grains, protruding from the surface of the resin layer, is about 70% or less of the average grain size of the abrasive grains, and a thickness deviation percentage of the resin layer with respect to the core wire is about 40%.